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In re the Application of: **Fumihiko TANIGUCHI et al.**

Serial Number: ~~Div of 09/335,878~~

09/836,182

Group Art Unit: 2822

Filed: **April 18, 2001**

Examiner: LIN, Y.

For: **METHOD OF FABRICATING SEMICONDUCTOR HAVING
THROUGH HOLE**

PRELIMINARY AMENDMENT

Director of Patents and Trademarks
Washington, D.C. 20231

April 26, 2001

Dear Sir:

Prior to examination in the above-identified divisional application, please amend the application as follows:

IN THE SPECIFICATION:

Match & Return

Please amend the specification, as follows:

Replace the paragraph starting at Page 1, line 29, with the following rewritten paragraph:

--The solder balls are arranged on the ball pads of the TAB tape and thus function as external electrodes. As a result, the semiconductor chip and the solder balls are electrically connected to each other by the TAB tape as an interposer. In the case where a semiconductor device of surface mount type having solder balls functioning as external terminals, such as a semiconductor device of BGA or CSP type, is mounted to a motherboard, the semiconductor device is, in general, heated in a solder reflowing equipment having an ambient temperature of about 250°C to connect the melted solder balls to the electrode pads of the motherboard.--

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